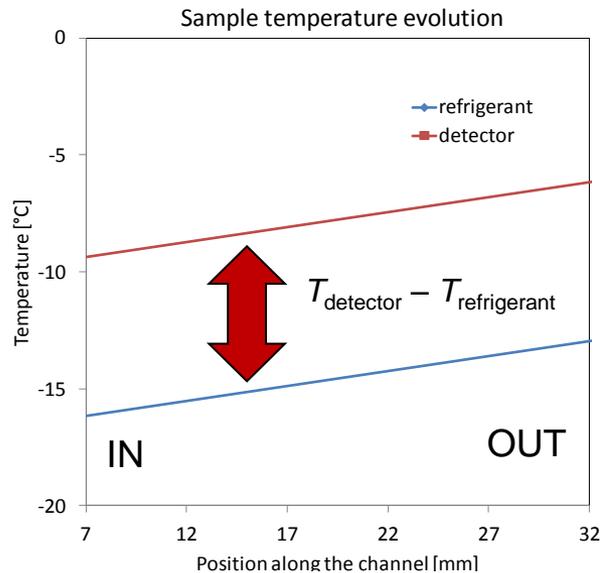


Minichannels for single-phase cooling

**- General considerations on
pressure drop and material budget -**



❑ The LOCAL temperature difference between detector and refrigerant depends on the LOCAL heat flux, refrigerant heat transfer coefficient and thermal resistance (glue, etc...).

❑ If heat flux, gluing and geometry are uniform, ($T_{\text{detector}} - T_{\text{refrigerant}}$) is uniform all along the stave.

❑ To a first approximation, the temperature variation is the same for the detector and the refrigerant.

❑ In order to achieve 5 K temperature uniformity on the detector, the refrigerant mass flow rate must be high enough to keep the refrigerant temperature rise $T_{\text{out}} - T_{\text{in}} < 5 \text{ K}$

$$Q = mc_p (T_{\text{out}} - T_{\text{in}})$$

❑ The minimum required mass flow rate depends on the specific heat c_p of the refrigerant.

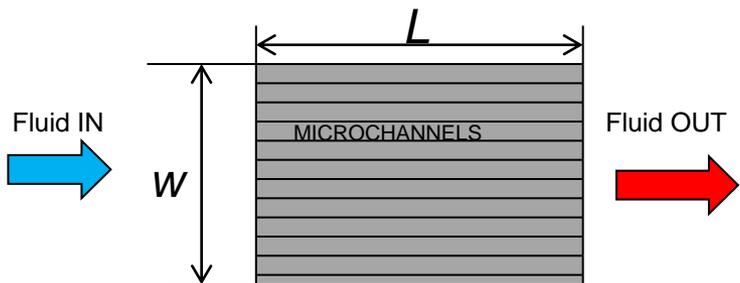
Low mass flow rate



Small channels



Low x/x_0



$w = 15 \text{ mm}$, $L = 210 - 370 \text{ mm}$
 C_6F_{14} : $c_p @ 15^\circ\text{C} = 1037 \text{ J kg}^{-1} \text{ K}^{-1}$
 water: $c_p @ 15^\circ\text{C} = 4188 \text{ J kg}^{-1} \text{ K}^{-1}$

Refrigerant	q [W cm ⁻²]	L [mm]	Q (per stave) [W]	m (per stave) [g/s]
C_6F_{14}	0.5	370	28	5.4
Water				1.3
$C_4F_{10}^*$ (2 bar)				0.6
CO_2^* (51 bar)				0.3
R717*(7 bar)				0.05

* Evaporative cooling examples, saturation temperature 15 °C, vapor quality in/out 0.2/0.7

- C_6F_{14} is a dielectric refrigerant.
- Water allows to decrease the mass flow rate by around 4 times as compared to C_6F_{14} .
- The mass flow rate with water is only double the mass flow rate required by evaporative cooling with C_4F_{10} .

Refrigerant Pressure Drop Constraint

- Water: < 0.5 bar in order to keep the pressure < 1 bar and avoid leakages
- C₆F₁₄: no constraints (dielectric fluid)

Material Pressure Constraint

- Silicon: 10 bar (pressure constraint for GTK/NA62 silicon microchannel cooling system)*
- Polyimide: ?
- The pressure constraint (and x/x_0) strongly depends on the thickness of the walls

x/x_0 due to Refrigerant Only

Single Channel $a \times b$

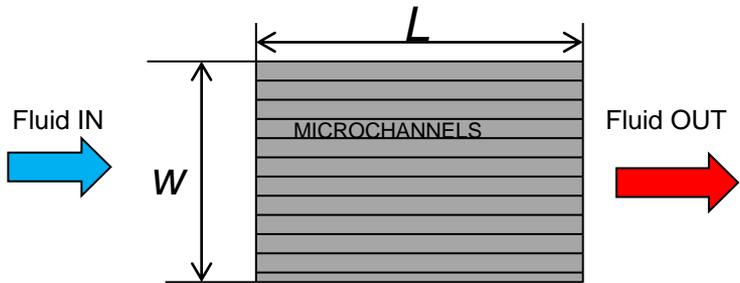
	a [μm]	b [μm]	channels	x/x_0 [%]	Pressure Drop [bar]
C ₆ F ₁₄	60	15000	1	0.03	9.5
C ₆ F ₁₄	160	15000	1	0.08	0.5
Water	53	15000	1	0.01	9.5
Water	140	15000	1	0.04	0.5

x_0 C₆F₁₄ = 0.19 m, x_0 water = 0.36 m

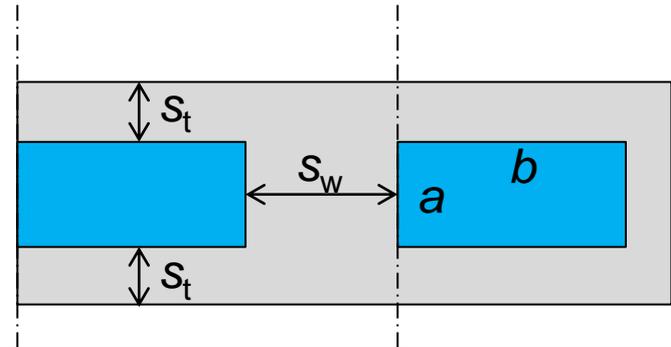
x_0 silicon = 0.09 m, x_0 polyimide = 0.29 m

* EDMS1157976 v.2

Constraints: refrigerant $\Delta T = 5K$, pressure drop < 10 bar



$w = 15 \text{ mm}$, $L = 210 \text{ mm}$, $q = 0.5 \text{ W cm}^{-2}$

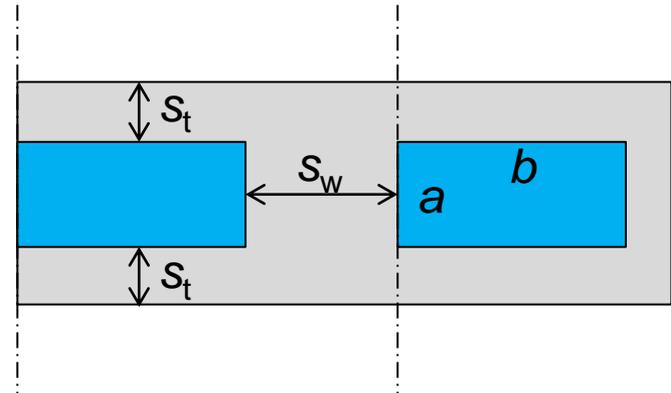
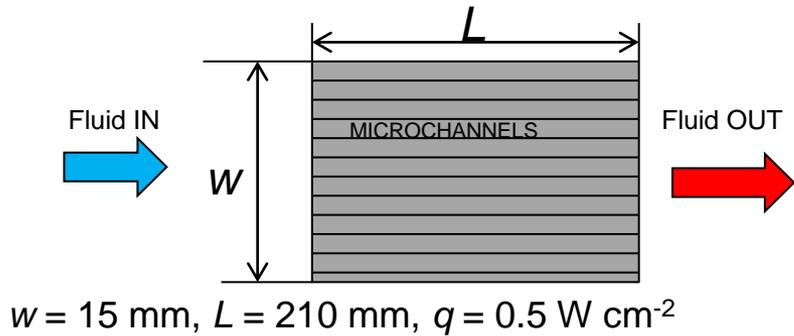


$x_0 \text{ silicon} = 0.094 \text{ m}$, $x_0 \text{ C}_6\text{F}_{14} = 0.190 \text{ m}$

a [μm]	b [μm]	s_t [μm]	s_w [μm]	channels	x/x_0 [%]	Pressure Drop [bar]
100	100	25	100	75	0.13	9.7
100	300	25	100	38	0.12	3.4
70	280	25	100	39	0.10	9.6

- 70~80% of the global x/x_0 is due to silicon.
- Some improvement can be obtained with high aspect ratio channels.

Constraints: refrigerant $\Delta T = 5K$, pressure drop < 0.5 bar

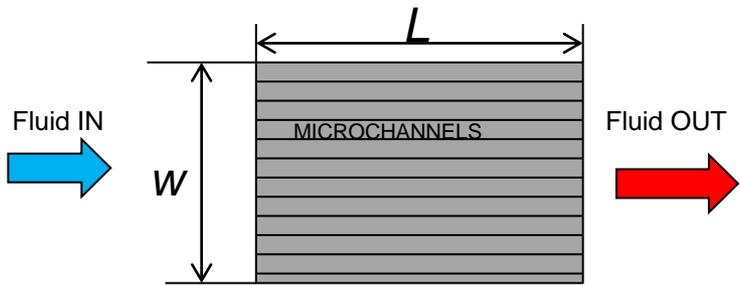


$x_0 \text{ silicon} = 0.094 \text{ m}, x_0 \text{ water} = 0.360 \text{ m}$

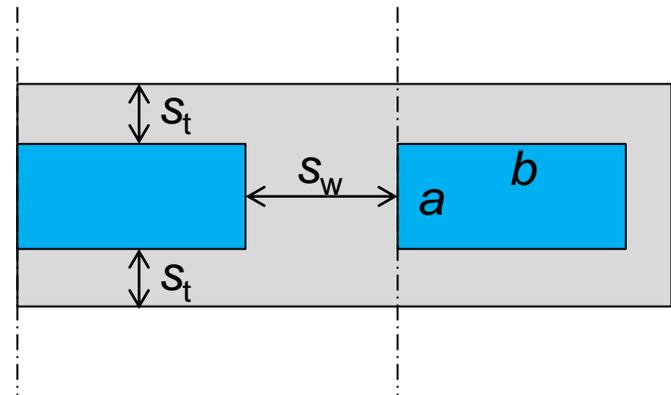
a [μm]	b [μm]	s_t [μm]	s_w [μm]	channels	x/x_0 [%]	Pressure Drop [bar]
210	210	25	100	48	0.17	0.5
210	630	25	100	21	0.13	0.2
160	480	25	100	26	0.12	0.5

☐ ~70% of the global x/x_0 is due to silicon.

Constraints: refrigerant $\Delta T = 5K$, pressure drop < 0.5 bar



$w = 15$ mm, $L = 210$ mm, $q = 0.5$ W cm⁻²



x_0 polyimide = 0.29 m, x_0 water = 0.36 m

a [μm]	b [μm]	s_t [μm]	s_w [μm]	channels	x/x_0 [%]	Pressure Drop [bar]
210	210	25	100	48	0.08	0.5
200	800	25	100	17	0.07	0.24
200	800	50	200	15	0.09	0.27

□ 30~50% of the global x/x_0 is due to polyimide.

Conclusions

- ❑ Water/ C_6F_{14} and silicon/polyimide have been considered.
- ❑ The maximum pressure drop and manufacturing constraints have a strong influence on the achievable x/x_0 .
- ❑ Water: low flow rate and high x_0 but pressure drop must be < 0.5 bar.
- ❑ C_6F_{14} : higher flow rate and lower x_0 , but higher pressure drop.
- ❑ Silicon: allows higher pressure but displays low x_0 .
- ❑ Polyimide: lower pressure allowed, but displays high x_0 .
- ❑ In order to reduce the x/x_0 , polyimide may be a better option for water and silicon may be a better option for C_6F_{14} .
- ❑ High aspect ratio channels allow to improve both pressure drop and x/x_0 .
- ❑ **x/x_0 reasonable target for silicon/ C_6F_{14} or polyimide/water: $\sim 0.10\%$**